

Notes:

1. Material:

Contact: High Performance Copper Alloy
 Shielding Cover: High Performance Copper Alloy
 Housing: High Temperature Thermoplastic.

2. Finish:

Contact: 30u" Nickel Underplating Overall. Au Plating on Contact Area
 Gold Flash on Solder Tail.
 Shielding Cover: 30u" Nickel Underplating Overall.
 See Order Information on Contact Area & Solder Tail.

3. Halogen-Free Product P/N:

C90P106-0000X-H

Shielding Cover Plating:

4: Gold Flash on contact area & solder tail.

5: Nickel plated on contact area. Gold flash on solder tail.

說明:

1. 材料:

訊號端子: 高性能銅合金
 外殼: 高性能銅合金
 塑膠: 高溫熱塑性塑膠

2. 電鍍:

訊號端子: 30u" 鍍底, 接觸區域鍍金, 錫鍍區域刷薄金
 外殼: 30u" 鍍底, 接觸區域及錫鍍區域電鍍如料號選項

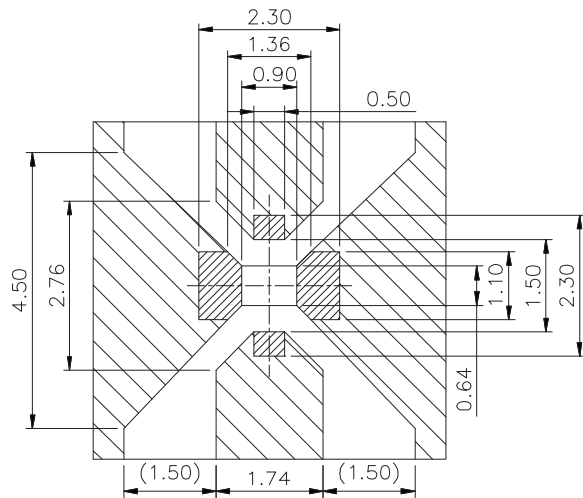
3. 無鹵料號:

C90P106-0000X-H

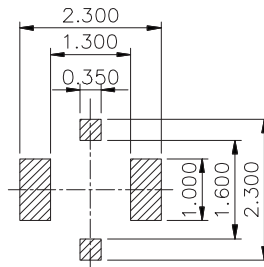
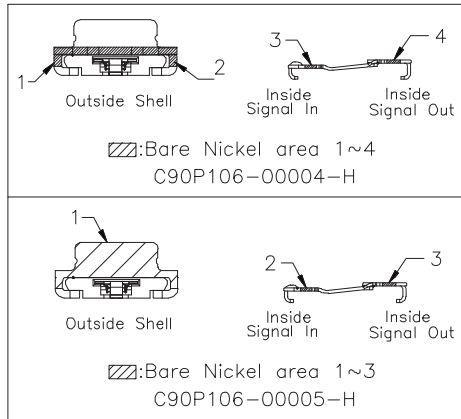
外殼電鍍:

4: 接觸區域與錫鍍區域鍍薄金.

5: 接觸區域鍍鍍, 錫鍍區域鍍薄金.

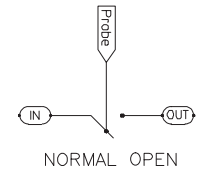
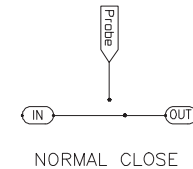
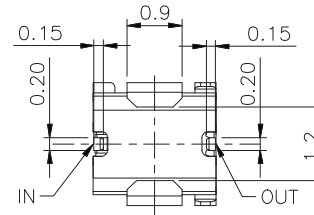
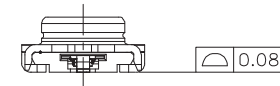
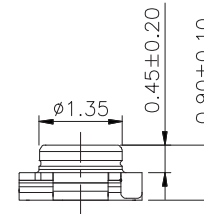
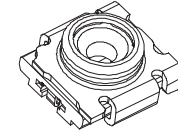
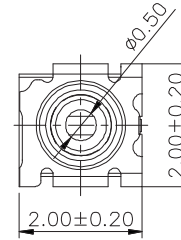


Recommend PCB Layout



Recommend Stencil Mask Pattern
 △ (Mask Thickness 0.08~0.10mm)

DCC ISSUE	Speedtech 2014.08.12 DCC 發行	REV	MODIFICATION	DATE	DRAW	APPROVE
		H	EN1308048	22-AUG-13	DANIEL	C.Y
		I	EN1311059	22-NOV-13	DANIEL	C.Y
		J	EN1408020	07-AUG-14	JAMES	Y.J



DIMENSION IN mm [Inch]		PROD. SPEC.		深圳市华灿天禄电子有限公司	
TOLERANCE UNLESS OTHERWISE SPECIFIED					
.X±0.25	X.°±5°	PKG. SPEC.	FILE NO.	DWG NO.	
.XX±0.10	.X°±3°			HC-RF-C90-106	
.XXX±0.06	.XX°±	TITLE RF Switch Connector		CUSTOMER DRAWING	
APPROVE	CHECK	DRAW	PROJ.	SHEET	1 / 1
Y.J	T.C	JAMES	SCALE 8:1	SIZE A4	REV J

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